

SDM2U30CSP

2A SCHOTTKY BARRIER RECTIFIER CHIP-SCALE PACKAGE

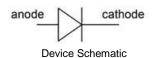
Product Summary

VRRM(V)	lo (A)	V _{F max} (V)	I _{R max} (μA)
30	2.0	0.48	150

Description and Applications

The SDM2U30CSP are 30-volt 2A Schottky barrier rectifiers that are optimized for low-forward voltage drop and low leakage current, housed in compact chip-scale package (CSP) that occupies only 1.28mm² board space with low profile. The low thermal resistance enables designers to meet design challenges of increasing efficiency whilst at the same time reducing board space. They are ideally suited for use in portable applications as:

- Blocking diodes
- Boost diodes
- Switching diodes
- Reverse protection diodes

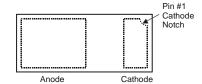


Features and Benefits

- Low-forward voltage (V_F) minimizes conduction losses and improves efficiency.
- Reduced high-temperature reverse leakage; Increased reliability against thermal runaway failure in high-temperature operation.
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Mechanical Data

- Package: X3-WLB1608-2
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiAu Bump. Solderable per MIL-STD-202, Method 208 @4)
- Polarity: Cathode Dot
- Weight: 0.001 grams (Approximate)



Ordering Information (Note 4)

Part Number	Dookers	Packing			
Part Number	Package	Qty.	Carrier		
SDM2U30CSP-7B	X3-WLB1608-2	10,000	Tape & Reel		
SDM2U30CSP-7	X3-WLB1608-2	5,000	Tape & Reel		

Notes:

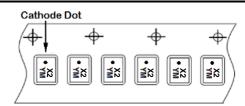
- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/. SDM2U30CSP-7B uses carrier tapes with 2mm pocket-to-pocket pitch; SDM2U30CSP-7 uses carrier tapes with 4mm pocket-to-pocket pitch.

Marking Information





X2= Product Type Marking Code YM=Date Code Marking Y or Y = Year (ex: L = 2024) M=Month (ex: 9= September) Dot Denotes Cathode Pin



Date Code Key

Year	2013	-	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033
Code	Α	-	L	М	N	Р	R	S	Т	U	V	W
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	VRRM	30	V
Average Rectified Output Current	lo	2.0	Α
Repetitive Peak Forward Current (Pulse Wave = 1 Sec, Duty Cycle = 66%)	I _{FRM}	4.2	А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine Wave Superimposed on Rated Load	IFSM	28	А

Thermal Characteristics

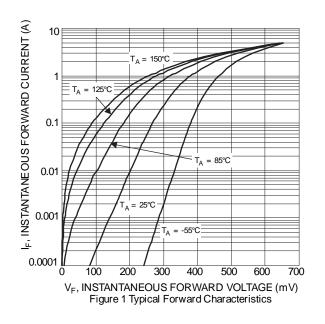
Characteristic	Symbol	Value	Unit	
Typical Thermal Resistance Junction to Ambient (Note 5)	R _θ JA	155	°C/W	
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C	

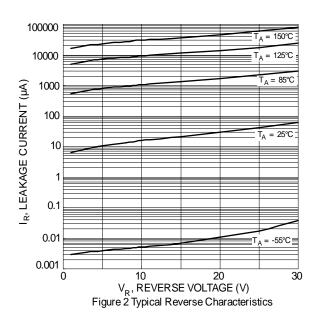
Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop	\/_		0.38	0.42	V	IF = 1.0A
Forward Voltage Drop	VF	_	0.45	0.48		IF = 2.0A
Reverse Current (Note 6)	IR	_	_	150	μA	V _R = 30V
Junction Capacitance	Сл	1	110	_	pF	V _R = 4V, f = 1.0MHz

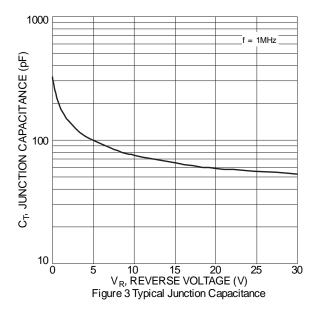
Notes: 5. Device

- $5.\ Device\ mounted\ on\ FR-4\ PCB,\ 2oz.\ Copper,\ minimum\ recommended\ pad\ layout\ per\ http://www.diodes.com/package-outlines.html.$
- 6. Short duration pulse test used to minimize self-heating effect.







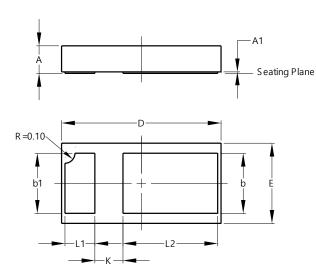




Package Outline Dimensions (Note 7)

Please see http://www.diodes.com/package-outlines.html for the latest version.

X3-WLB1608-2



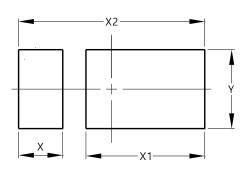
X3-WLB1608-2						
Dim	Min	Max	Тур			
Α	0.250	0.300	0.275			
A1	-	0.015	-			
b	-	-	0.600			
b1	-	-	0.600			
D	1.57	1.63	1.60			
Е	0.77	0.83	0.80			
K	-	-	0.282			
L1	0.25	0.35	0.30			
L2	0.90	1.00	0.95			
All Dimensions in mm						

Note 7: Device side walls are electrically active bare silicon. Avoid contact of solder or flux on the side walls during the PCB assembly process.

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X3-WLB1608-2



Dimensions	Value		
Dillielisions	(in mm)		
Х	0.385		
X1	1.035		
X2	1.622		
Y	0.690		



IMPORTANT NOTICE

- 1. DIODES INCORPORATED (Diodes) AND ITS SUBSIDIARIES MAKE NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO ANY INFORMATION CONTAINED IN THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).
- 2. The Information contained herein is for informational purpose only and is provided only to illustrate the operation of Diodes' products described herein and application examples. Diodes does not assume any liability arising out of the application or use of this document or any product described herein. This document is intended for skilled and technically trained engineering customers and users who design with Diodes' products. Diodes' products may be used to facilitate safety-related applications; however, in all instances customers and users are responsible for (a) selecting the appropriate Diodes products for their applications, (b) evaluating the suitability of Diodes' products for their intended applications, (c) ensuring their applications, which incorporate Diodes' products, comply the applicable legal and regulatory requirements as well as safety and functional-safety related standards, and (d) ensuring they design with appropriate safeguards (including testing, validation, quality control techniques, redundancy, malfunction prevention, and appropriate treatment for aging degradation) to minimize the risks associated with their applications.
- 3. Diodes assumes no liability for any application-related information, support, assistance or feedback that may be provided by Diodes from time to time. Any customer or user of this document or products described herein will assume all risks and liabilities associated with such use, and will hold Diodes and all companies whose products are represented herein or on Diodes' websites, harmless against all damages and liabilities.
- 4. Products described herein may be covered by one or more United States, international or foreign patents and pending patent applications. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks and trademark applications. Diodes does not convey any license under any of its intellectual property rights or the rights of any third parties (including third parties whose products and services may be described in this document or on Diodes' website) under this document.
- provided Diodes' products are subject to Diodes' Standard Terms and Conditions of Sale (https://www.diodes.com/about/company/terms-and-conditions/terms-and-conditions-of-sales/) or other applicable terms. This document does not alter or expand the applicable warranties provided by Diodes. Diodes does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel.
- 6. Diodes' products and technology may not be used for or incorporated into any products or systems whose manufacture, use or sale is prohibited under any applicable laws and regulations. Should customers or users use Diodes' products in contravention of any applicable laws or regulations, or for any unintended or unauthorized application, customers and users will (a) be solely responsible for any damages, losses or penalties arising in connection therewith or as a result thereof, and (b) indemnify and hold Diodes and its representatives and agents harmless against any and all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim relating to any noncompliance with the applicable laws and regulations, as well as any unintended or unauthorized application.
- 7. While efforts have been made to ensure the information contained in this document is accurate, complete and current, it may contain technical inaccuracies, omissions and typographical errors. Diodes does not warrant that information contained in this document is error-free and Diodes is under no obligation to update or otherwise correct this information. Notwithstanding the foregoing, Diodes reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes.
- 8. Any unauthorized copying, modification, distribution, transmission, display or other use of this document (or any portion hereof) is prohibited. Diodes assumes no responsibility for any losses incurred by the customers or users or any third parties arising from any such unauthorized use.
- 9. This Notice may be periodically updated with the most recent version available at https://www.diodes.com/about/company/terms-and-conditions/important-notice

The Diodes logo is a registered trademark of Diodes Incorporated in the United States and other countries. All other trademarks are the property of their respective owners.

© 2024 Diodes Incorporated. All Rights Reserved.

www.diodes.com

SDM2U30CSP Document number: DS36600 Rev. 11 - 2